

Remarks

Currently pending in the application are claims 14-18 and 20-27. Claims 14, 20 and 27 have been amended to further define the present invention. Support for these amendments can be found at, for example, claim 19 and paragraph [0024] of the present application. No new matter has been added.

35 U.S.C. § 103(a)

The Examiner rejected claims 14-27 as being unpatentable over Koyanagi et al. (JP 2002-338652). Applicants traverse this rejection for the following reasons.

Koyanagi et al. teaches a photosensitive resin composition containing a polyurethane compound formed from:

- (A) an epoxy carboxylate compound obtained by reacting an epoxy compound with a monocarboxylic acid having an ethylenically unsaturated group;
- (B) a carboxylic acid compound having two hydroxyl groups; and
- (C) a diisocyanate compound.

The photosensitive composition taught in Koyanagi et al. may also contain a photopolymerization initiator, a hardening component, and a cross-linking agent. Koyanagi et al. however does not teach or suggest a photosensitive resin composition containing a linear, crosslinkable polyurethane polymer obtained from monomers comprising at least one aliphatic or cycloaliphatic diol having 2 to 30 carbon atoms, to whose carbon chain one or more carboxyl groups have been covalently bonded, and some or all of the carboxyl groups have been esterified with an olefinically unsaturated C₃-C₈ alcohol or with a glycidyl ester of an olefinically unsaturated C₃-C₈ carboxylic acid and which also includes radicals of at least one aliphatic, cycloaliphatic or cycloaliphatic-

aliphatic diol, or at least one oligomeric or polymeric oxaalkylene glycol, or a polyesterdiol, or a polycarbonatediol, or a polylactonediol or a diol based on polybutadiene or polyisoprene as presently claimed.

Furthermore, Koyanagi et al. neither teaches or suggests that the use of such an additional diol as defined in element a) iii) in claims 14 and 27 and element c) in claim 20 leads to an improved shock resistance and a low stripping time in photocurable linear, crosslinkable polyurethane compositions used in the field of etch resist, solder masks or liquid dielectric (see Table on page 12 of the present published application).

It is respectfully submitted that claims 14-18 and 20-27 are patentable and are in a condition for allowance. Applicants respectfully request all pending claims be allowed and that the application pass to issuance.

The Commissioner of Patents is hereby authorized to deduct any fee due in connection with the filing of this document from Huntsman Corporation Deposit Account No. 08-3442.

Respectfully Submitted,

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